

ABSTRACT

EPOXY RESIN COMPOSITION AND
SEMICONDUCTOR DEVICE USING THE SAME

The present invention provides an epoxy resin composition for encapsulating a semiconductor, which has excellent flame retardancy without containing any flame retardant such as halogen type, antimony trioxide or the like. The present invention lies in an epoxy resin composition for encapsulating a semiconductor, comprising as essential components:

(A) a phenolic resin containing, in the total phenolic resin amount, 30 to 100% by weight of a phenolic resin of novolac structure containing, in the molecule, a biphenyl derivative and/or a naphthalene derivative,

(B) an epoxy resin containing, in the total epoxy resin amount, 30 to 100% by weight of an epoxy resin of novolac structure containing, in the molecule, a biphenyl derivative and/or a naphthalene derivative,

(C) an inorganic filler, and

(D) a curing accelerator.